

holding portion being wider than the wiring path;
laying a wire in the wiring path of the wiring board such
that a leader of the wire, including any bent portion thereof, is
held in the holding portion of the wiring board as the wire is
laid; and

combining the first and second casings with the wiring board located therebetween.

10. (New) The method according to claim 9, wherein said wiring path comprises a laying groove, and said holding portion comprises a holding recess that is wider than the laying groove.

11. (New) The method according to claim 9, wherein said holding recess is extended on both sides of the laying groove in a width direction of the laying groove.--